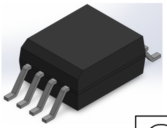
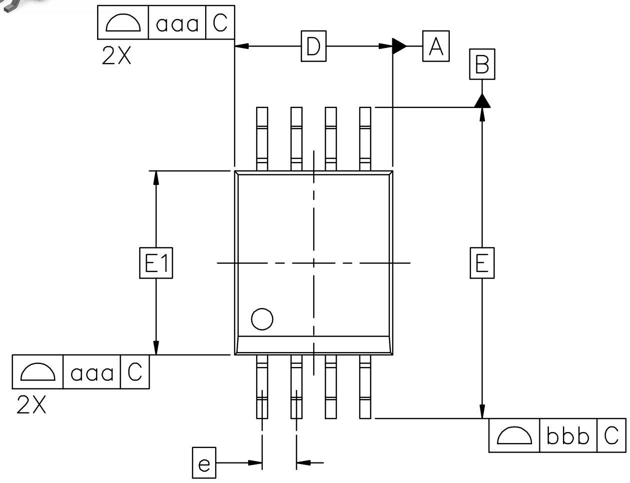
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

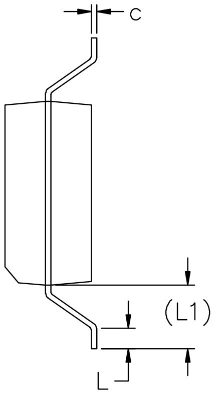


SOIC/LSOP-8 5.84x6.80x3.18, 1.27P
CASE 751FC
ISSUE O

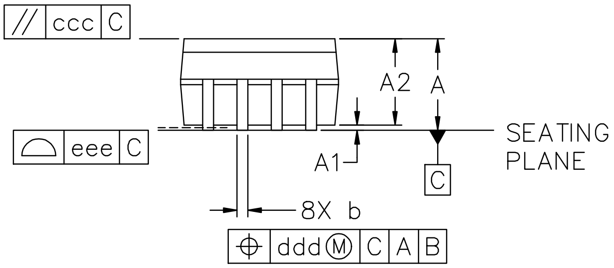
DATE 02 FEB 2026



TOP VIEW

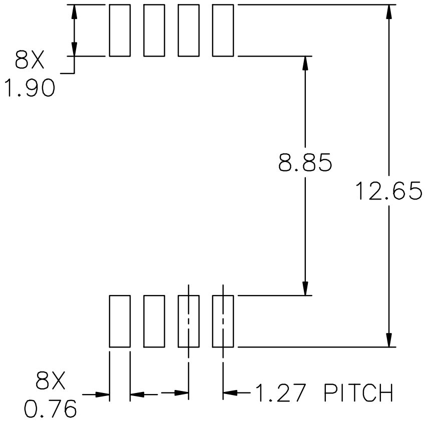


SIDE VIEW



END VIEW

MILLIMETERS			
DIM	MIN	NOM	MAX
A	3.18	3.38	3.58
A1	0.10	0.20	0.30
A2	3.08	3.18	3.28
b	0.30	0.40	0.50
c	0.20	0.25	0.30
D	5.84 BSC		
E	11.50 BSC		
E1	6.80 BSC		
e	1.27 BSC		
L	0.50	0.75	1.00
L1	2.35 REF		
POSITION FORM & TOLERANCE			
aaa	0.20		
bbb	0.25		
ccc	0.10		
ddd	0.25		
eee	0.10		



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb−Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:
1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.

DOCUMENT NUMBER:	**98AON73214H**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	**SOIC/LSOP-8 5.84x6.80x3.18, 1.27P**	**PAGE 1 OF 1**